XN04602

Silicon NPN epitaxial planar type (Tr1)
Silicon PNP epitaxial planar type (Tr2)

For general amplification

■ Features

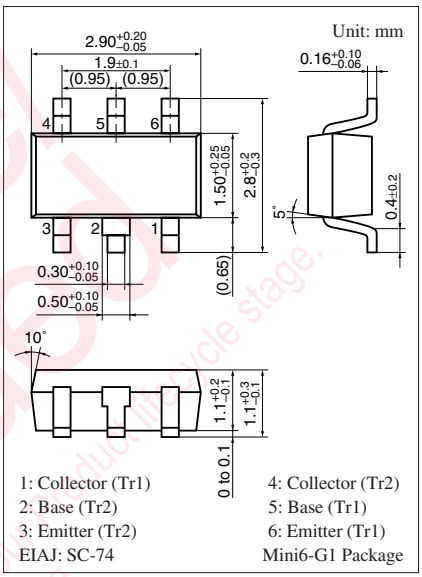
- Two elements incorporated into one package
- Reduction of the mounting area and assembly cost by one half

■ Basic Part Number

- 2SD0602A + 2SB0710A

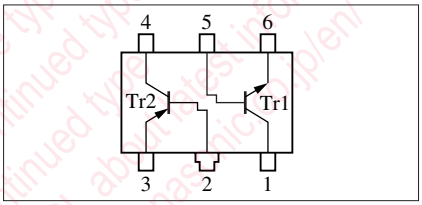
■ Absolute Maximum Ratings $T_a = 25°C$

	Parameter	Symbol	Rating	Unit
Tr1	Collector-base voltage (Emitter open)	V_{CBO}	60	V
	Collector-emitter voltage (Base open)	V_{CEO}	50	V
	Emitter-base voltage (Collector open)	V_{EBO}	5	V
	Collector current	I_C	0.5	A
	Peak collector current	I_{CP}	1	A
Tr2	Collector-base voltage (Emitter open)	V_{CBO}	−60	V
	Collector-emitter voltage (Base open)	V_{CEO}	−50	V
	Emitter-base voltage (Collector open)	V_{EBO}	−5	V
	Collector current	I_C	− 0.5	A
	Peak collector current	I_{CP}	−1	A
Overall	Total power dissipation	P_T	300	mW
	Junction temperature	T_j	150	°C
	Storage temperature	T_{stg}	−55 to +150	°C



Marking Symbol: 4A

Internal Connection



■ Electrical Characteristics $T_a = 25°C \pm 3°C$

• Tr1

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = 10\ \mu A$, $I_E = 0$	60			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = 10$ mA, $I_B = 0$	50			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10\ \mu A$, $I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 20$ V, $I_E = 0$			0.1	μA
Forward current transfer ratio *	h_{FE1}	$V_{CE} = 10$ V, $I_C = 150$ mA	85		340	—
	h_{FE2}	$V_{CE} = 10$ V, $I_C = 500$ mA	40			
Collector-emitter saturation voltage *	$V_{CE(sat)}$	$I_C = 300$ mA, $I_B = 30$ mA		0.35	0.60	V
Transition frequency	f_T	$V_{CB} = 10$ V, $I_E = -50$ mA, f = 200 MHz		200		MHz
Collector output capacitance (Common base, input open circuited)	C_{ob}	$V_{CB} = 10$ V, $I_E = 0$, f = 1 MHz		6	15	pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.
2. *: Pulse measurement

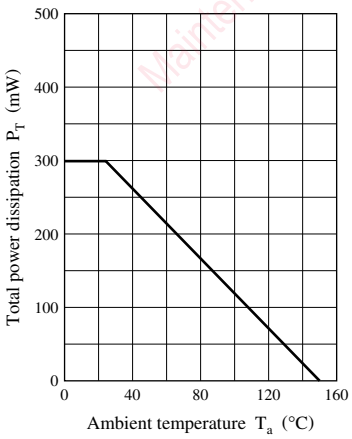
• Tr2

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = -10\ \mu A$, $I_E = 0$	−60			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = -10$ mA, $I_B = 0$	−50			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = -10\ \mu A$, $I_C = 0$	−5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -20$ V, $I_E = 0$			− 0.1	μA
Forward current transfer ratio	h_{FE1}	$V_{CE} = -10$ V, $I_C = -150$ mA	85		340	—
	h_{FE2}	$V_{CE} = -10$ V, $I_C = -500$ mA	40			
Collector-emitter saturation voltage *	$V_{CE(sat)}$	$I_C = -300$ mA, $I_B = -30$ mA		− 0.35	− 0.60	V
Base-emitter saturation voltage *	$V_{BE(sat)}$	$I_C = -300$ mA, $I_B = -30$ mA		−1.1	−1.5	V
Transition frequency	f_T	$V_{CB} = -10$ V, $I_E = 50$ mA, f = 200 MHz		200		MHz
Collector output capacitance (Common base, input open circuited)	C_{ob}	$V_{CB} = -10$ V, $I_E = 0$, f = 1 MHz		6	15	pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.
2. *: Pulse measurement

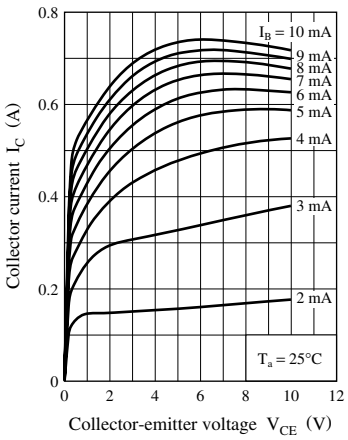
Common characteristics chart

P_T — T_a

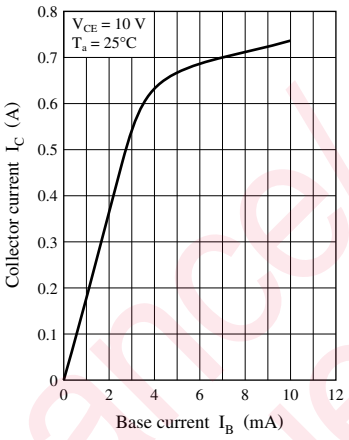


Characteristics charts of Tr1

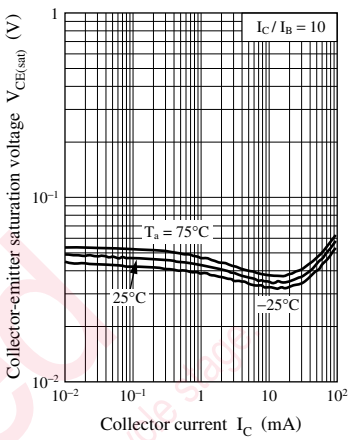
I_C — V_{CE}



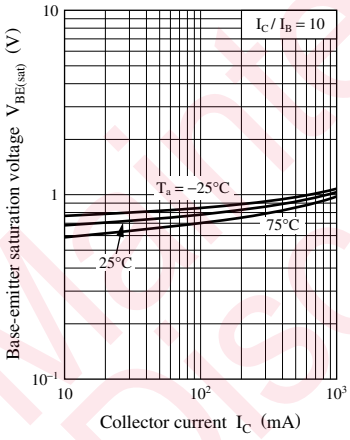
I_C — I_B



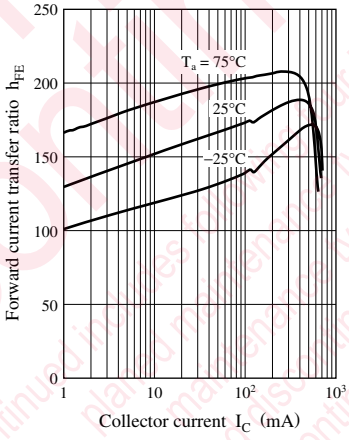
$V_{CE(sat)}$ — I_C



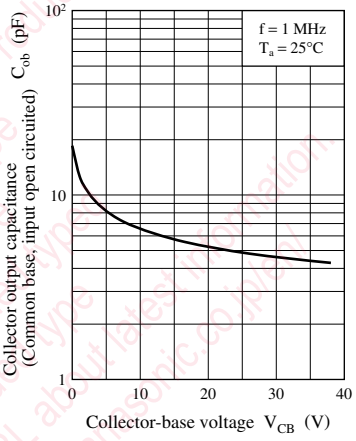
$V_{BE(sat)}$ — I_C



h_{FE} — I_C

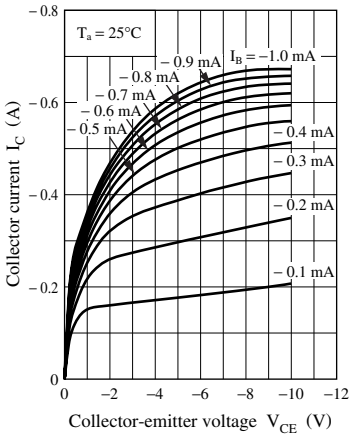


C_{ob} — V_{CB}

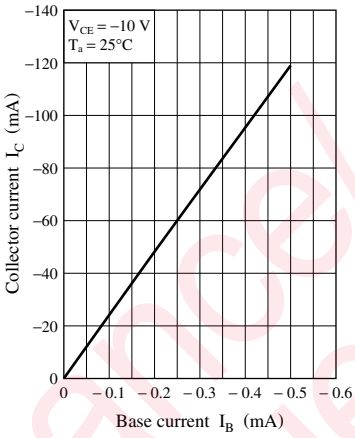


Characteristics charts of Tr2

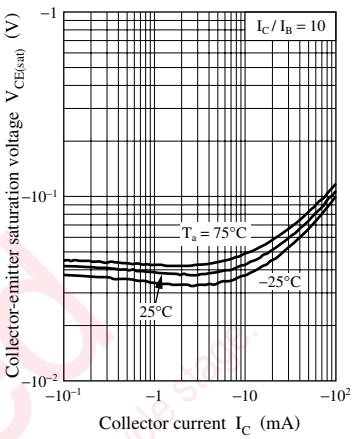
I_C — V_{CE}



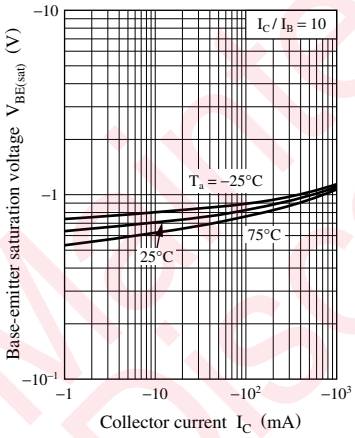
I_C — I_B



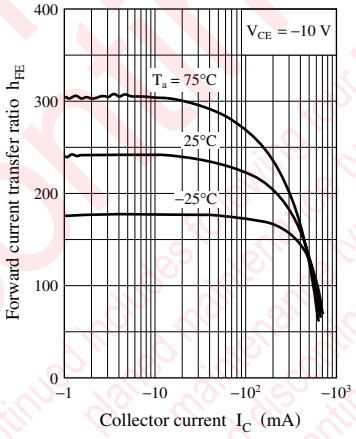
$V_{CE(sat)}$ — I_C



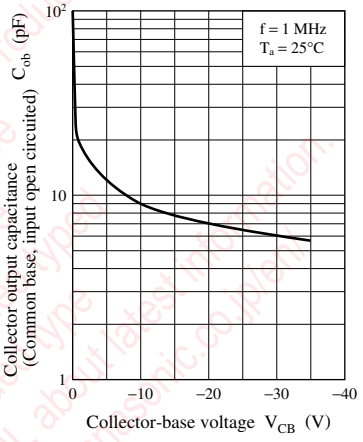
$V_{BE(sat)}$ — I_C



h_{FE} — I_C



C_{ob} — V_{CB}



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